

**PLEASE AMEND THE CLAIMS AS INDICATED BELOW:**

1. (Currently Amended) A method for encapsulating leadframe items each comprising an IC mounted on a leadframe, the method comprising:  
loading pellets of plastics material from a pellet holder into a pellet dispenser;  
conveying ~~one or more~~ a leadframe ~~item~~ items to a ~~mould~~ mold;  
dispensing at least one pellet of plastics material from the pellet dispenser; and  
~~mould~~ molding the dispensed plastics material of the ~~at least one dispensed pellet~~ around the leadframe;

~~wherein the method further comprises at least one step of removing dust of the plastics material from the pellet holder and from the pellet dispenser.~~

2. (Currently Amended) A method according to claim 1 in which the step of removing the plastics dust includes brushing the pellet holder and the pellet dispenser.

3. (Original) A method according to claim 1 in which the step of removing plastics dust includes applying a vacuum source to the pellet holder and the pellet dispenser.

4-6. (Canceled)

7. (Currently Amended) A method for encapsulating leadframe items each comprising an IC mounted on a leadframe, the method comprising:  
conveying one or more leadframe items to a ~~mould~~ mold;  
dispensing at least one pellet of plastics material; and  
~~mould~~ molding the dispensed plastics material ~~of the dispensed pellet~~ around the leadframe;  
wherein the leadframe is conveyed to the ~~mould~~ mold by a conveyor while exposed to a pressure source which is in communication with a cover of the conveyor whereby dust of the plastics material is removed from the leadframe.

8. (Original) A method according to claim 7 in which the pressure source is a vacuum source.

9. (Currently Amended) A method for encapsulating leadframe items each comprising an IC mounted on a leadframe, the method comprising:  
displacing a door from a first position in which the door closes a ~~mould~~ molding region to a second position in which the door does not close the ~~mould~~ molding region, thereby opening a path to the ~~mould~~ molding region;  
conveying one or more leadframe items along the path to a ~~mould~~ mold located in the ~~mould~~ molding region while the door is at the second position;  
returning the door to the first position;  
dispensing at least one pellet of plastics material; and  
~~mould~~ molding the dispensed plastics material ~~of the dispensed pellet~~ around the leadframe item.

10. (Currently Amended) A method for encapsulating leadframe items each comprising an IC mounted on a leadframe, the method comprising:  
conveying one or more leadframe items to a ~~mould~~ mold;  
dispensing at least one pellet of plastics material; and  
~~mould~~ molding the dispensed plastics material ~~of the dispensed pellet~~ around the leadframe;  
~~wherein the method further comprises using a brush member to~~ applying a brush to at least one surface of the ~~mould~~ mold to remove dust of the plastics material from the ~~mould~~ mold, and thereafter,  
removing dust from the brush by applying a vacuum source to the brush at an end position traveled by the brush.

11. (Canceled)

12. (Currently Amended/Withdrawn) A system for encapsulating leadframe items each comprising an IC mounted of a leadframe, the system comprising:  
a pellet holder for holding pellets of plastics material;

a pellet dispenser for receiving the pellets from the pellet holder and dispensing them to a ~~mould~~ mold;

a conveyor for conveying at least one leadframe item to the ~~mould~~ mold;

means for ~~mould~~ molding the plastics material of the at least one ~~dispensed~~ dispensed pellet around the leadframe; and

a cleaning device for removing dust of the plastics material from the pellet holder.

13. (Withdrawn) A system according to claim 12 in which the cleaning device includes a brush member for brushing the pellet holder.

14. (Currently Amended/Withdrawn) A ~~method~~ system according to claim 12 in which the cleaning device includes a vacuum source.

15. (Currently Amended/Withdrawn) A system for encapsulating leadframe items each comprising an IC mounted on a leadframe, the system comprising:

a conveyor for conveying one or more leadframe items to a ~~mould~~ mold;

a pellet dispenser for dispensing at least one pellet of plastics material to the ~~mould~~ mold;

means for ~~mould~~ molding the plastics material of the at least one dispensed pellet around the leadframe; and

at least one cleaning device for removing dust of the plastics material from the pellet dispenser.

16. (Withdrawn) A system according to claim 15 in which the cleaning device includes a brush for brushing the pellet dispenser.

17. (Currently Amended/Withdrawn) A system according to claim 15 in which the cleaning device includes a vacuum source ~~sources~~.

18. (Currently Amended/Withdrawn) A system for encapsulating leadframe items each comprising an IC mounted on a leadframe, the system comprising:

a conveyor for conveying at least one leadframe item to a ~~mould~~ mold;

a pellet dispenser for dispensing at least one pellet of plastics material;

means for ~~mould~~ molding the plastics material of the dispensed pellet around the leadframe;

and

a pressure source;

the conveyor including a cover in communication with the pressure source and for covering the leadframe item whereby dust of the plastics material is removed from the leadframe item.

19. (Withdrawn) A system according to claim 18 in which the pressure source is a vacuum source.

20. (Currently Amended/Withdrawn) A system for encapsulating leadframe items each comprising:

a door;

an actuator for displacing the door from a first position in which the door closes a ~~mould~~ molding region to a second position in which the door does not close the ~~mould~~ molding region, thereby opening a path to the ~~mould~~ molding region;

a conveyor for conveying at least one leadframe item along the path to a ~~mould~~ mold located in the ~~mould~~ molding region;

a pellet dispenser for dispensing at least one pellet of plastics material;

means for ~~mould~~ molding the plastics material of the dispensed pellet around the leadframe;

and

a controller arranged to control the actuator to displace the door from the first position to the second position when the conveyor is to operate, and otherwise to control the actuator to displace the door from the second to the first position.

21. (Currently Amended/Withdrawn) A system for encapsulating leadframe items each comprising an IC mounted on a leadframe, the system comprising:

a conveyor for conveying one or more leadframe items to a ~~mould~~ mold;  
a pellet dispenser for dispensing at least one pellet of plastics material;  
means for ~~mould~~ molding the plastics material of the dispensed pellet around the leadframe;  
a brush member arranged to brush at least one surface of the ~~mould~~ mold to remove dust of the plastics material from the ~~mould~~ mold.

22. (Withdrawn) A system according to claim 21 further including a vacuum source arranged to suck dust from the brush.

23. (New) A method according to claim 1 in which the step of removing the plastics dust includes the steps of:

brushing the pellet holder and/or the pellet dispenser with a brush; and  
applying a vacuum source proximate to the brush to remove plastics dust therefrom.